



Material Content Data Sheet



Sales Product Name				BSC035N04LS G		Issued		23. January 2018	
MA#				MA001636012					
Package				PG-TDSON-8-39		Weight*		112.52 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.840	1.64	1.64	16353	16353	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		130		
	non noble metal	iron	7439-89-6	0.049	0.04		433		
	non noble metal	copper	7440-50-8	48.649	43.25	43.30	432351	432914	
	non noble metal	copper	7440-50-8	0.045	0.04	0.04	396	396	
wire	non noble metal	copper	7440-50-8	0.045	0.04	0.04	396	396	
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		733		
	plastics	epoxy resin	-	6.520	5.79		57945		
	inorganic material	silicondioxide	60676-86-0	34.664	30.81	36.67	308064	366742	
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13509	13509	
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1408	1408	
solder	non noble metal	tin	7440-31-5	0.038	0.03		337		
	noble metal	silver	7440-22-4	0.047	0.04		422		
	non noble metal	lead	7439-92-1	1.813	1.61	1.68	16109	16868	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		150		
	noble metal	silver	7440-22-4	0.150	0.13		1333		
	non noble metal	copper	7440-50-8	16.910	15.03	15.18	150282	151810	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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